

## PATENT ABSTRACTS OF JAPAN

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### (54) POSITIVE PHOTOSENSITIVE RESIN COMPOSITION

#### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a photosensitive resin composition developable with an alkali aqueous solution, having high sensitivity, easily forming a patterned thin film excellent in various characteristics such as flatness, high resolution, developing property, heat resistance, solvent resistance, adhesion property to a substrate, transparency, insulating property and so on, and moreover, to provide a photosensitive resin composition easily forming a patterned thin film having excellent low dielectric characteristics as well as the above characteristics.

**SOLUTION:** The positive photosensitive resin composition is characterized by containing at least an alkali-soluble resin comprising a copolymer containing at least N-(4-hydroxyphenyl) maleimide by 50 mol%, a compound having a 1,2- naphthoquinone diazide group and a crosslinking agent.